

ABSTRACT OF THE DISCLOSURE

A method of bonding a cover plate over OLED devices formed on a surface of a device substrate wherein each one of the OLED devices includes at least one electrical interconnect area includes providing a flow-preventing pattern
5 on a surface of the cover plate or on the OLED devices absent from the electrical interconnect areas of the OLED devices to prevent flow of a flowable adhesive material into at least the outermost portions of such interconnect areas; dispensing a selected amount of a flowable curable adhesive material on the surface of the cover plate in registration with the flow-preventing pattern; engaging the cover
10 plate in alignment with the substrate; and curing the adhesive material.